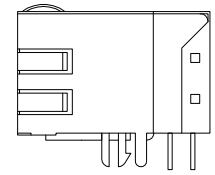
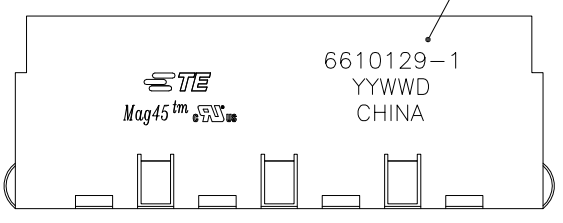
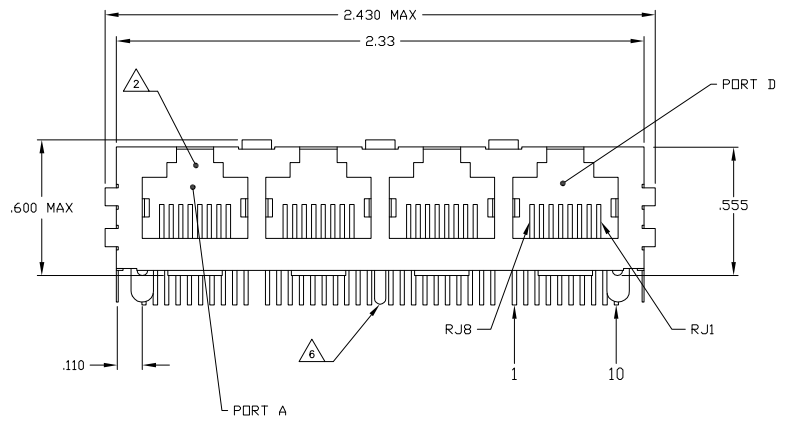


LOC	DIST	REV	DESCRIPTION	DATE	BY	APP
AA	22	C	REV PER ECO-08-015415	12APR2008	DC	TX
		D	ECO-11-013422	20MAY2011	EL	LR

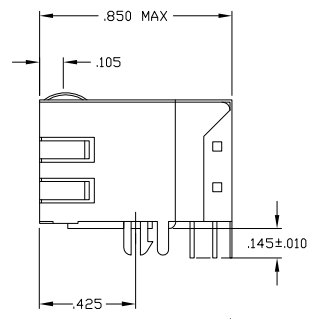
MECHANICAL:



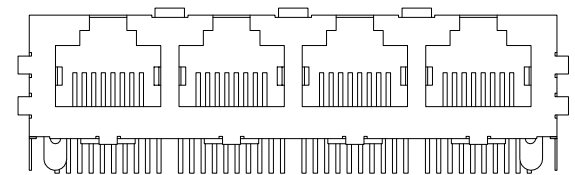
6610129-1 ONLY
NO BOTTOM TABS AND NO REAR GROUND PIN



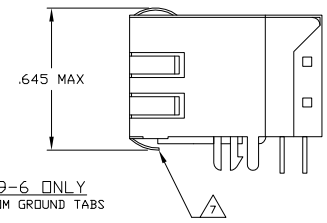
6610129-5 SHOWN WITH REAR GROUND PIN



1X4 SUGGESTED PANEL CUTOUT



1610129-6 ONLY WITH BOTTOM GROUND TABS



- 1 MATERIALS:
 - HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
 - SHIELD - .010" THICK C26800 BRASS PREPLATED WITH 30µINCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100µINCH MIN SAC SOLDER.
 - MOD JACK CONTACTS - .0157" X .018", PHOSPHOR BRONZE, 50µINCH MIN OVERALL NICKEL UNDERPLATE, WITH SELECT 50µINCH MIN HARD GOLD FINISH PLATE. SOLDER TAILS WITH 1000µINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
- 2 RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.
- 3 MAGNETICS:
 - APPLICATION: 10/100/1000 BASE-T
 - IMPEDANCE: 100 OHMS
 - TURNS RATIO (CHIP:CABLE): 1:1 ALL FOUR PAIRS
 - OPEN CIRCUIT INDUCTANCE (OCL): 350µH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, ALL FOUR PAIRS
 - ALL FOUR PAIRS BI-DIRECTIONAL
 - PERFORMANCE @ 25°C:
 - INSERTION LOSS (IL): 1dB MAX FROM 0.5MHz TO 100MHz
 - RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 4.0MHz
 - 12-20LOG(f/80)dB MIN FROM 4.0MHz TO 100MHz
 - CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 4.0MHz
 - 33-20LOG(f/50)dB MIN FROM 4.0MHz TO 100MHz
 - COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 - ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC AND WITH ALL PORTS CONNECTED.
- 4 OPERATING TEMPERATURE: FROM 0°C TO -70°C.
- 5 INDICATED MAGNETIC CONNECTIONS ARE SYMMETRICAL TO ACCOMMODATE CONNECTIONS FOR EITHER NIC OR HUB CONFIGURATION, OR SUPPORT AUTO-MDI/MDIX.
- 6 REAR GROUND PIN ON 6610129-5 ONLY.
- 7 BOTTOM GROUND TABS ON 6610129-6 ONLY.
- 8 TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN
- 9 THESE PARTS ARE RECOMMENDED FOR WAVE SOLDERING PROCESS, PEAK WAVE SOLDERING TEMPERATURE IS 265°C MAX, 10 SECONDS MAX.

4	0	6610129-6
0	1	6610129-5
0	0	6610129-1
△ BOTTOM PANEL GROUND TAB	△ REAR PCB GROUND TAB	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT. DWG. BY: B. GRZYBOWSKI, DESIGNED BY: B. GRZYBOWSKI, CHECKED BY: D. FAROLE, APPROVED BY: D. FAROLE.

TE Connectivity

1X4 MAG45(TM) MODULAR JACK, 7C4 GIGABIT SCHEMATIC (10 PIN HORIZONTAL), 7C05 SERIES CIRCUIT, SHIELDED, NO LEADS

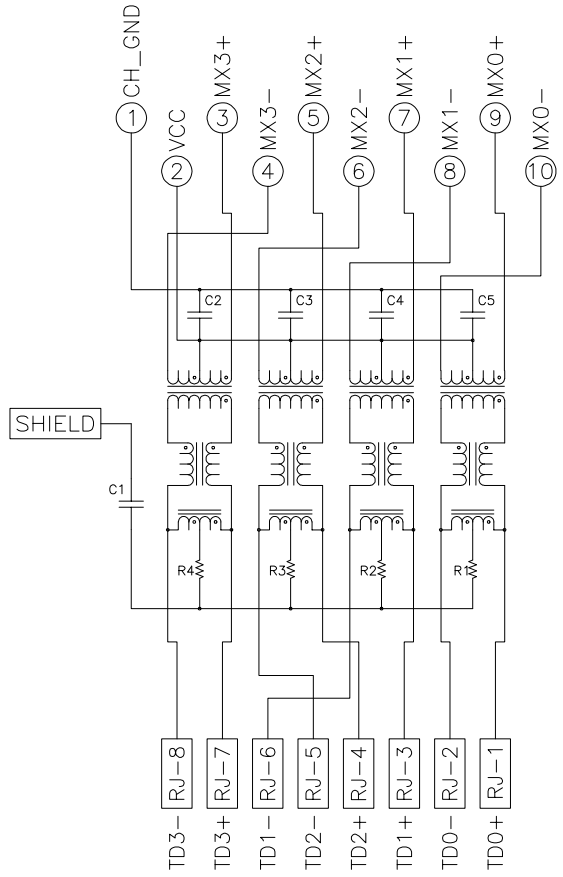
108-2100

SIZE: A1, CAGE CODE: 00779, DRAWING NO: 6610129

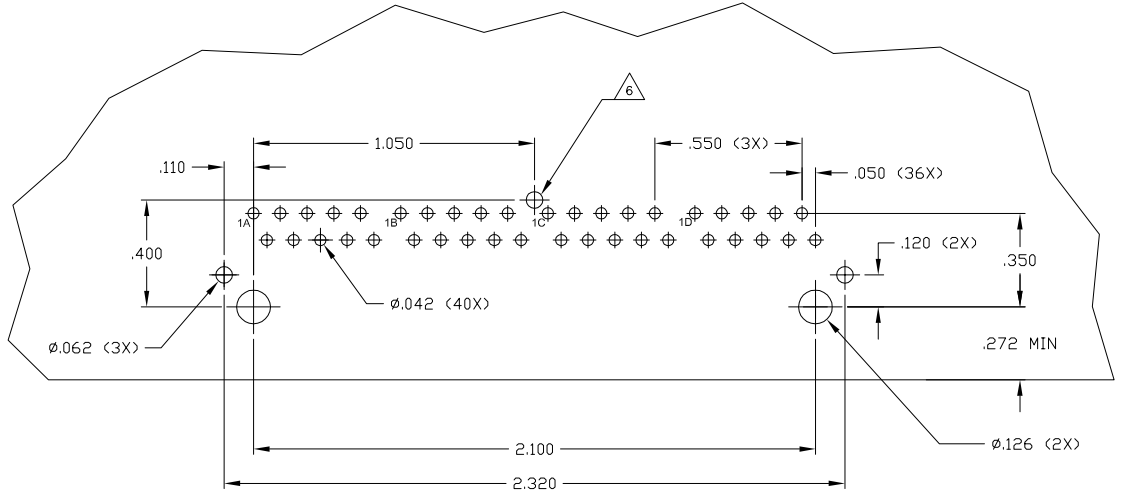
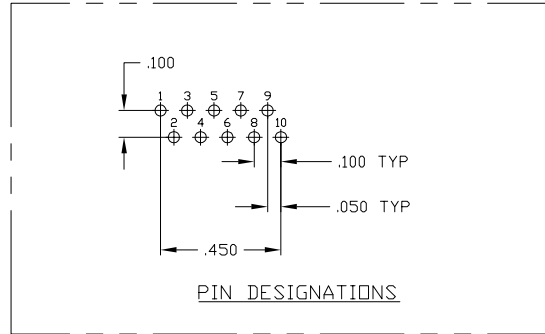
MATERIAL: CUSTOMER DRAWING

SCALE: 1:1, SHEET: 1 of 2, REV: D

7G05 SERIES GIGABIT MAGNETIC CIRCUIT



C1 = 1000 pF, 2kV CAPACITOR
 R1-R4 = 75 OHMS, 1/16W RESISTORS
 C2-C5 = 0.1μF, 50V, X7R CAPACITORS



SUGGESTED PCB LAYOUT
 (Component Side)

THIS DRAWING IS A CONTROLLED DOCUMENT.		DESIGNED BY: R. GRZYBOWSKI	DATE: 10/20/10
DRAWN BY: D. FAROLE		CHECKED BY: D. FAROLE	DATE: 10/20/10
APPROVED BY: D. FAROLE		DESIGNER NAME: D. FAROLE	DATE: 10/20/10
PRODUCT SPEC: 108-2100		APPLICATION SPEC: 108-2100	DATE: 10/20/10
MATERIAL: SEE SHEET 1		FINISH: SEE SHEET 1	WEIGHT: -
SIZE: A1		QTY CODE: 00779	DRAWING NO: C=6610129
CUSTOMER DRAWING		SCALE: 1:1	SHEET: 2 OF 2